

Reshaping and Forging silicon/silicon alloy members

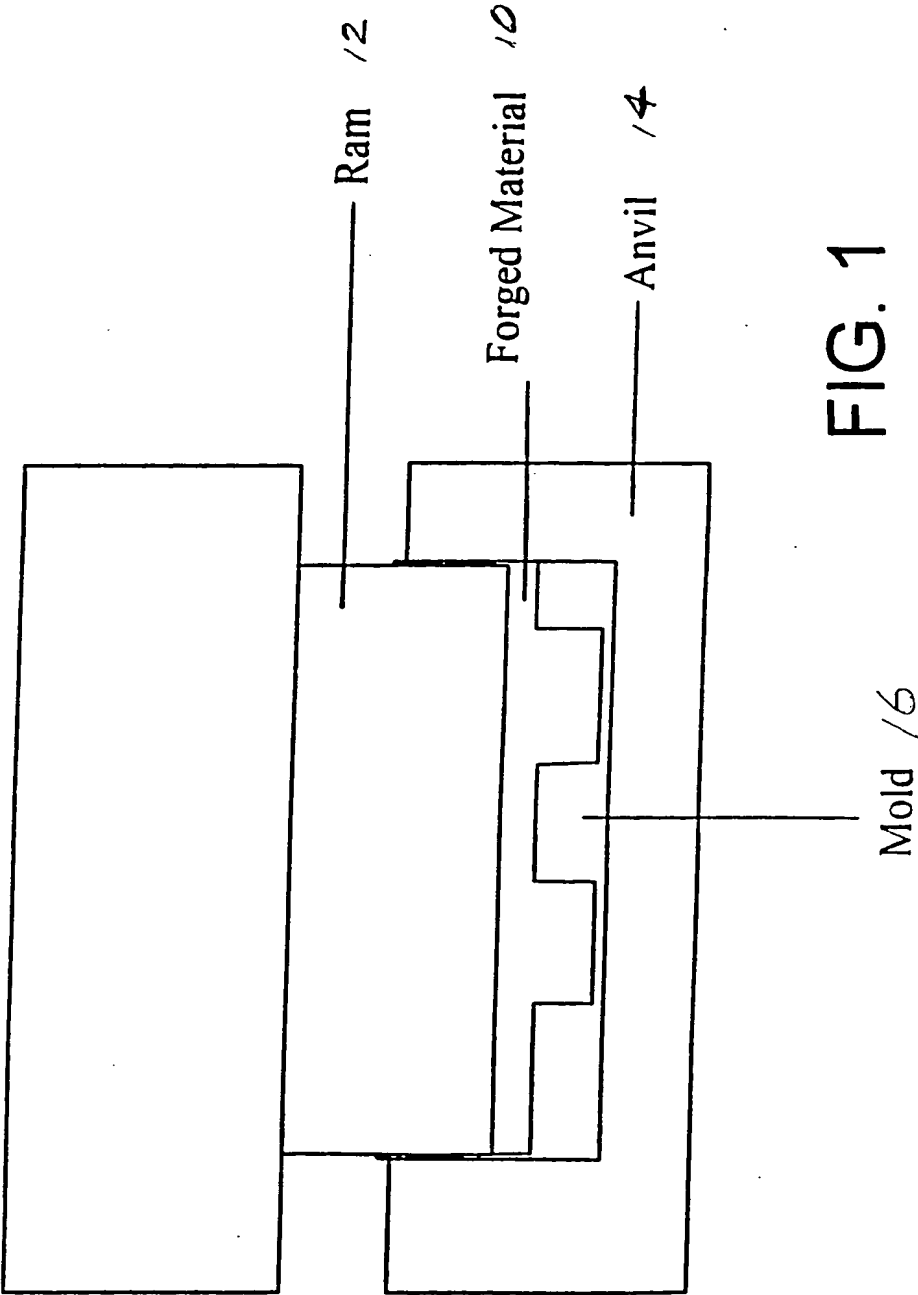


FIG. 1

High temperature vacuum/special gas atmosphere reshaping and forging silicon/silicon alloy members

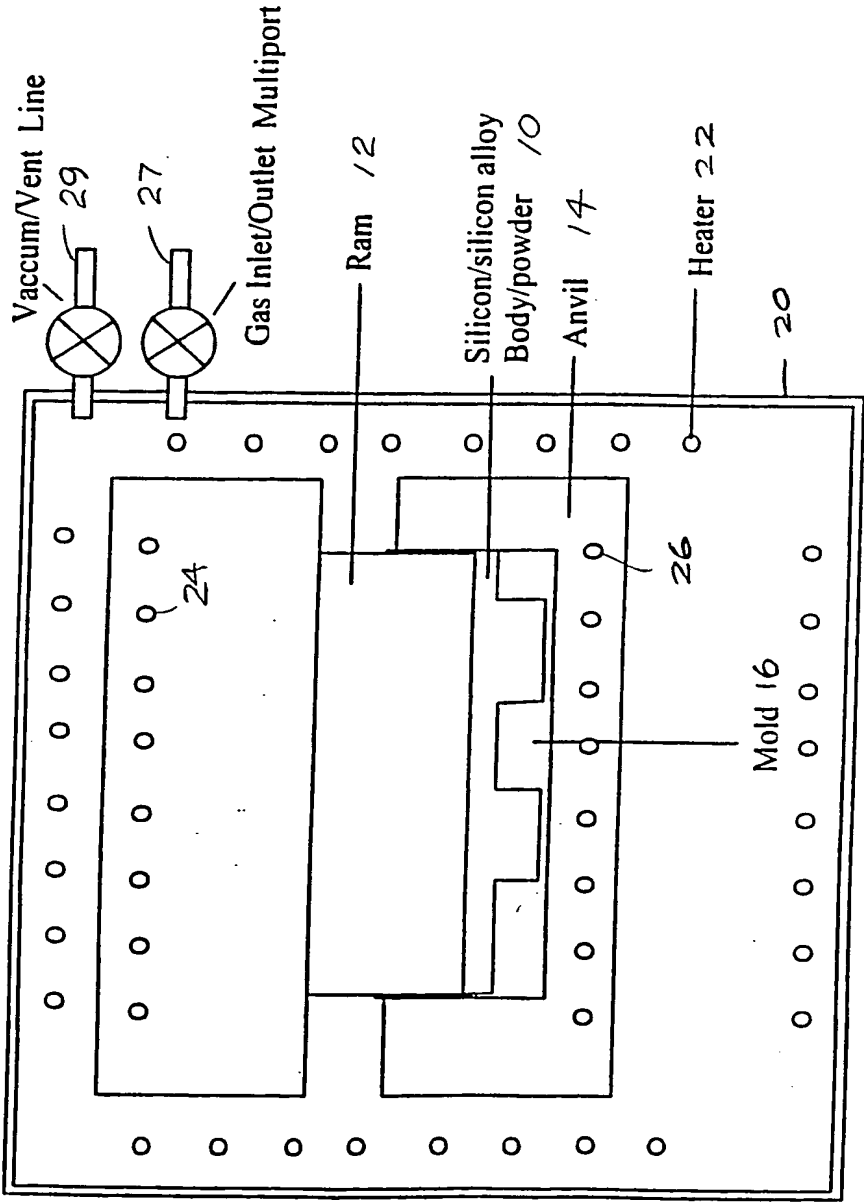


FIG. 2

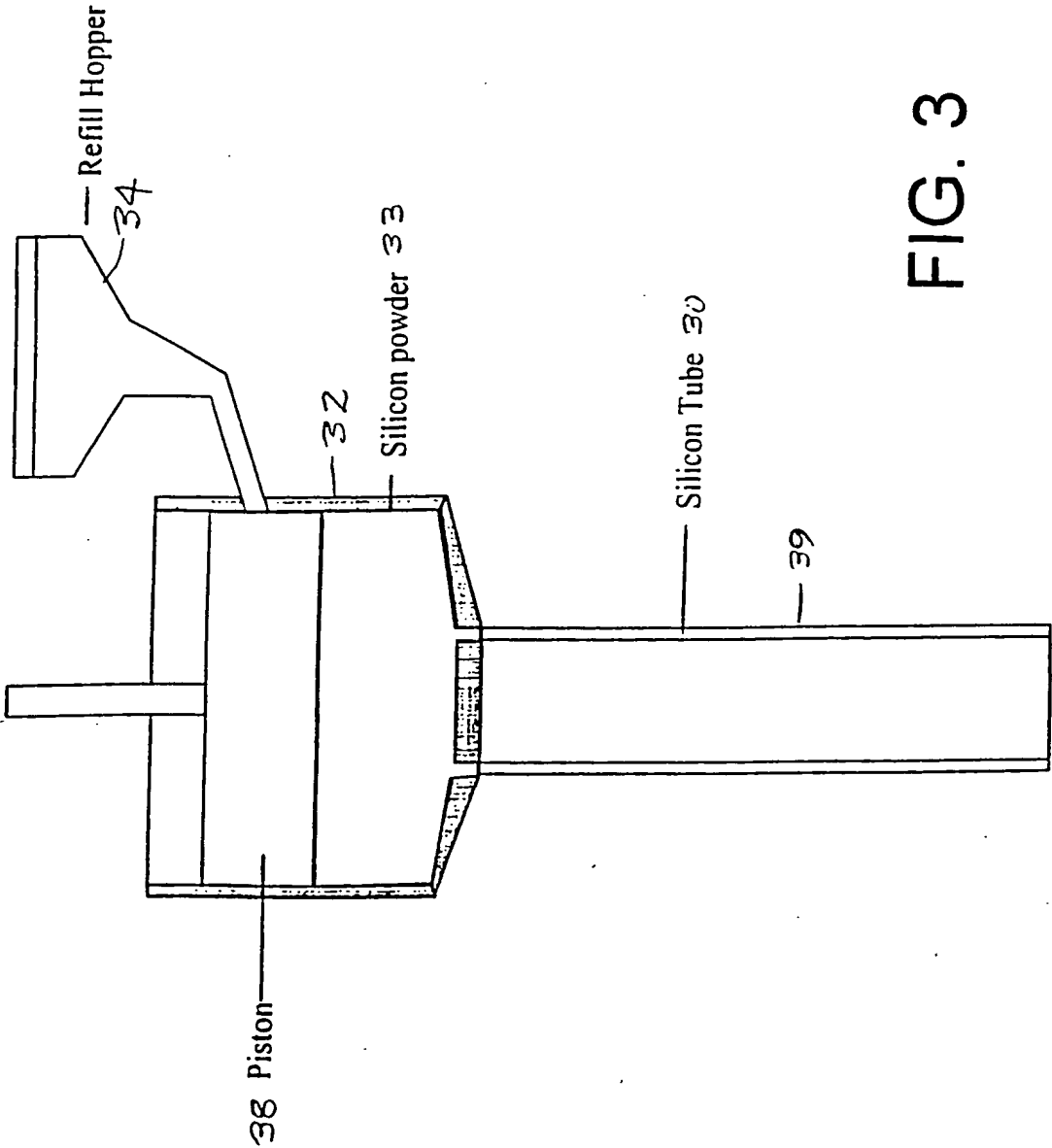


FIG. 3

4/20

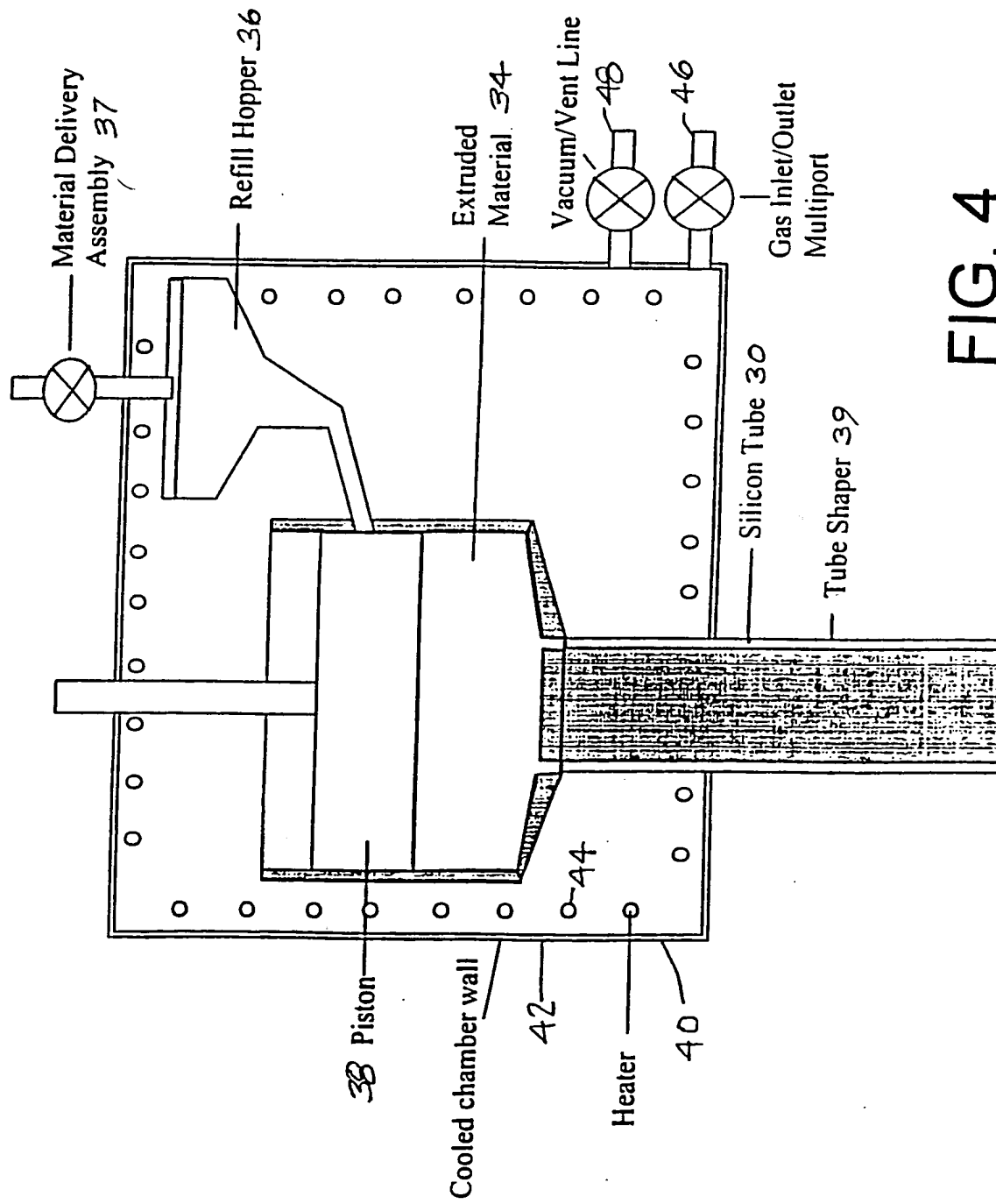


FIG. 4

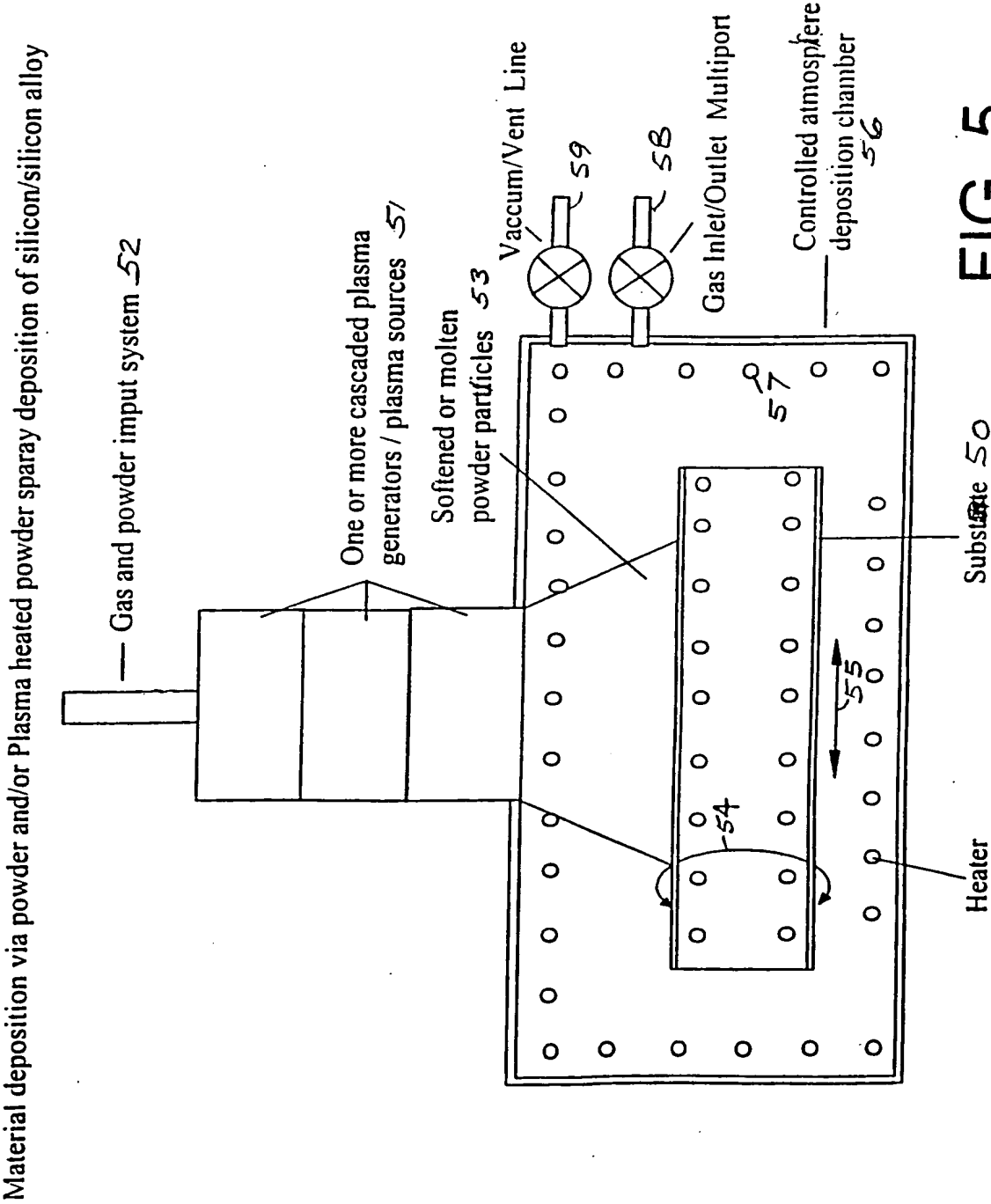


FIG. 5

Silicon / silicon alloy slurry spray silicon member fabrication method

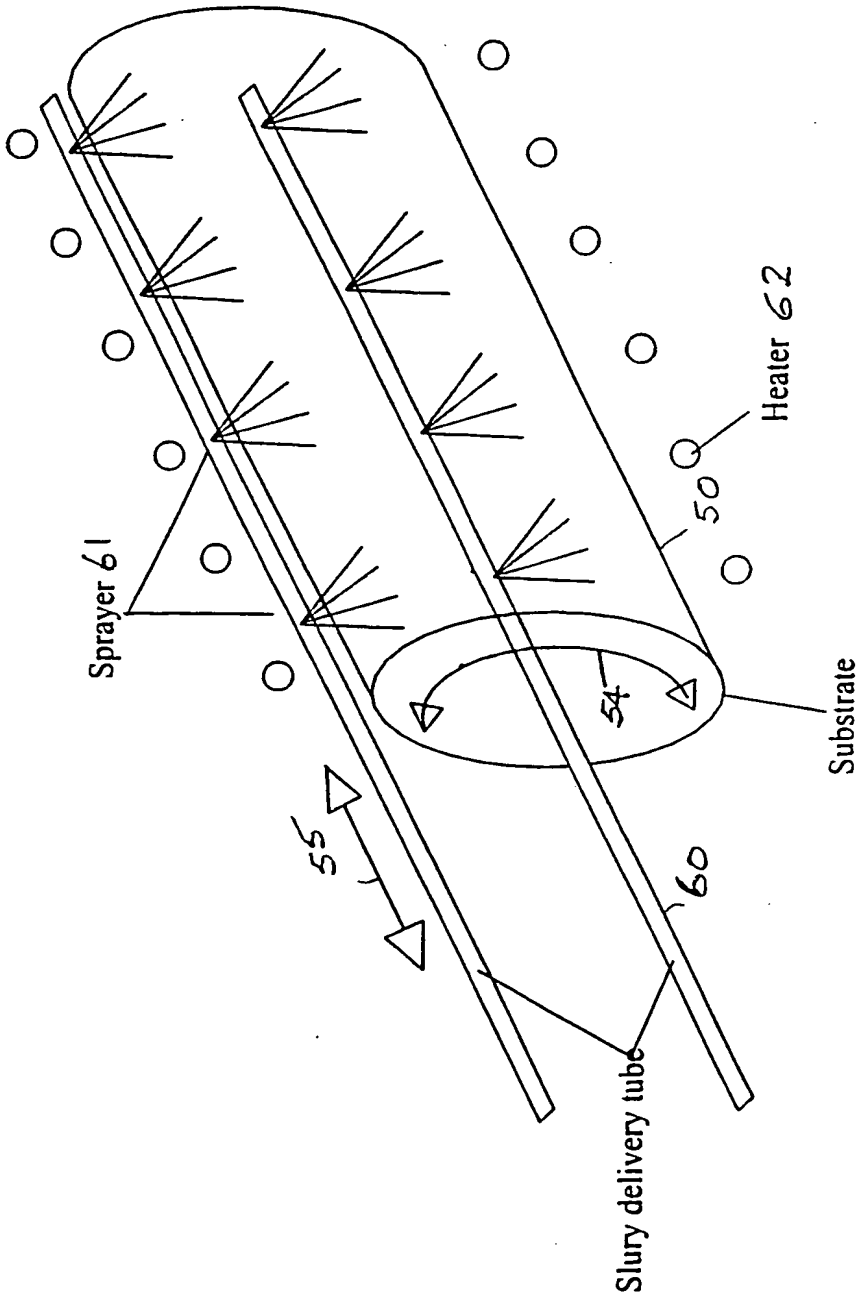


FIG. 6

Silicon / silicon alloy tubing for liner or wafer boat fabrication

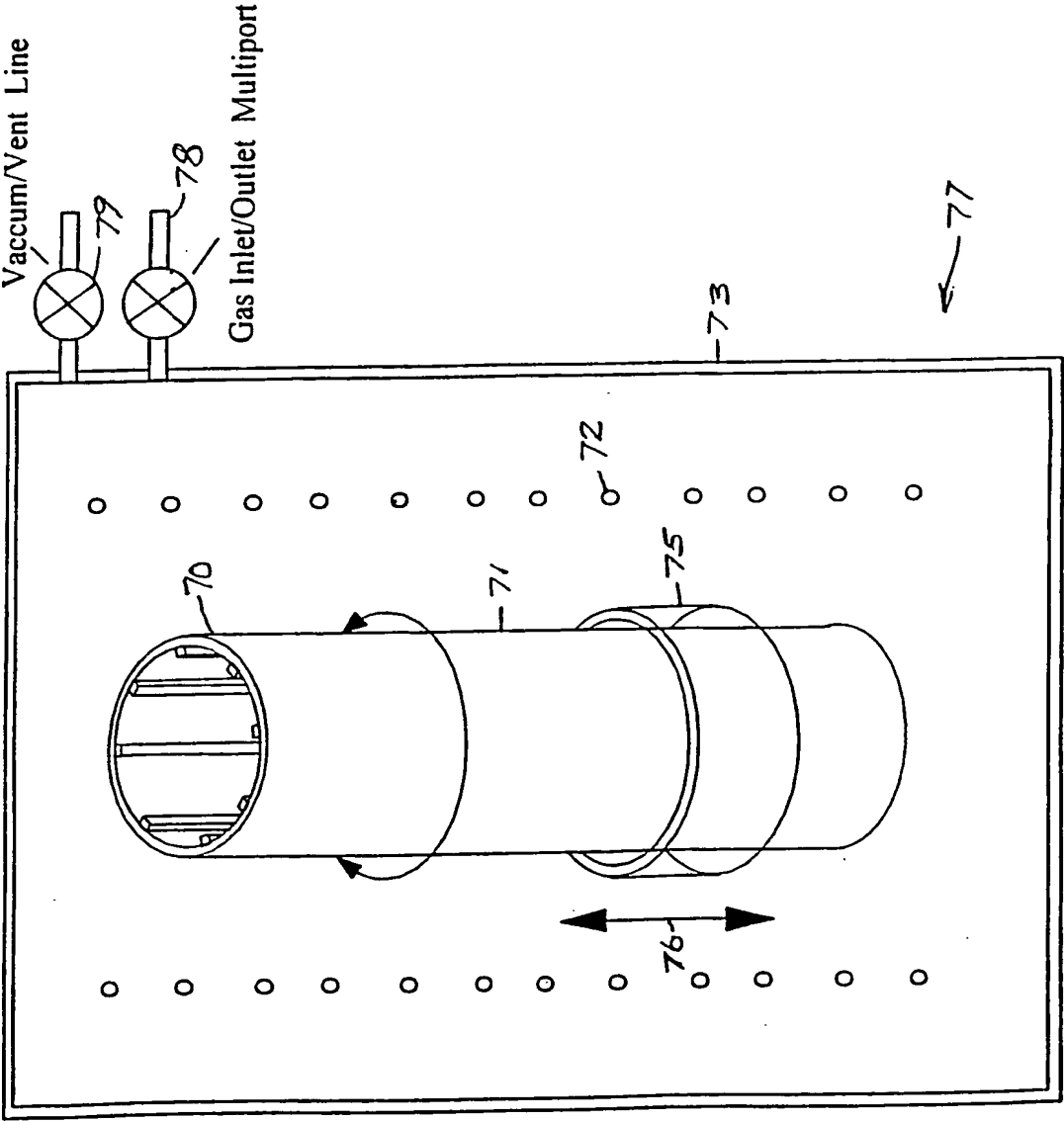


FIG. 7

Silicon / silicon alloy tubing for liner or wafer boat fabrication

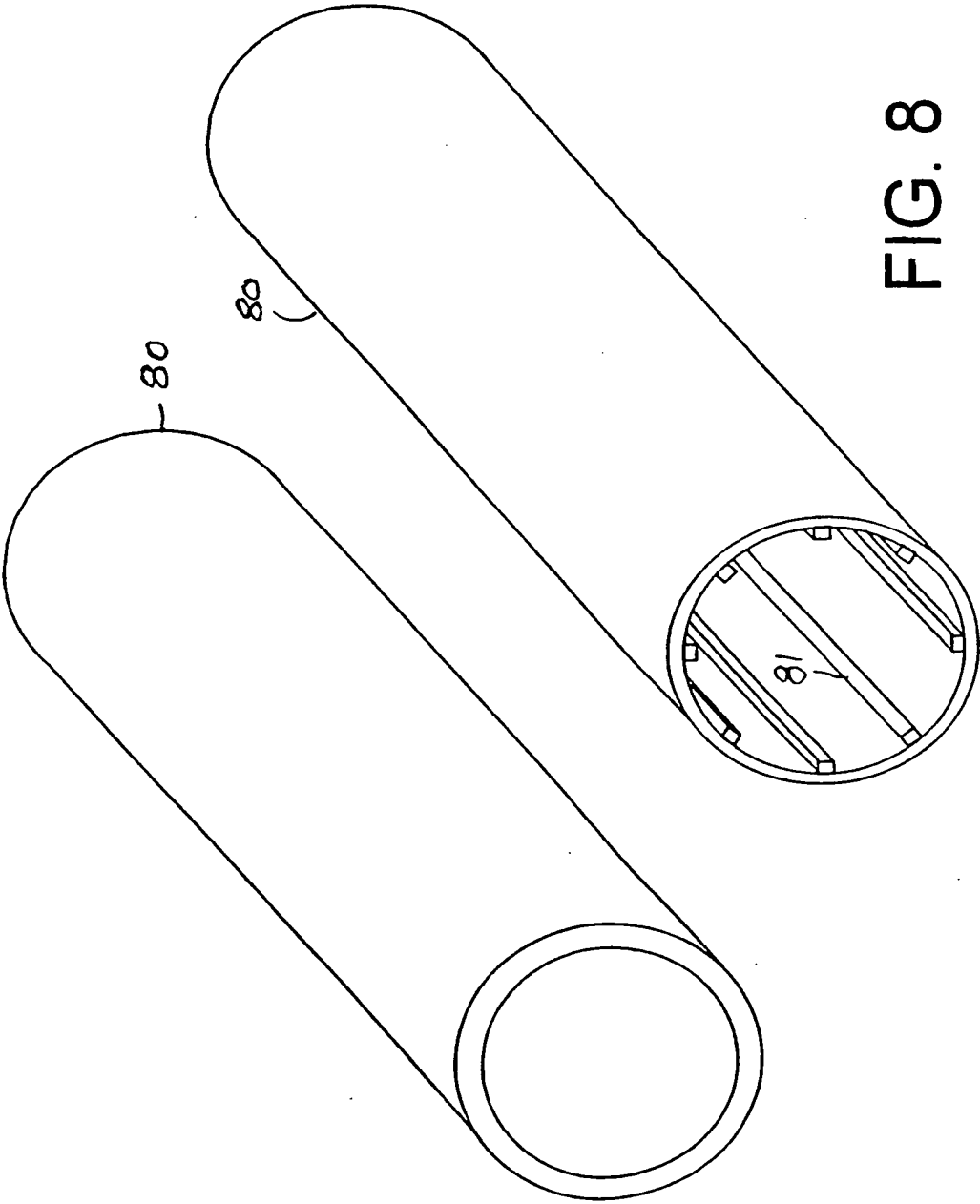


FIG. 8

9/20

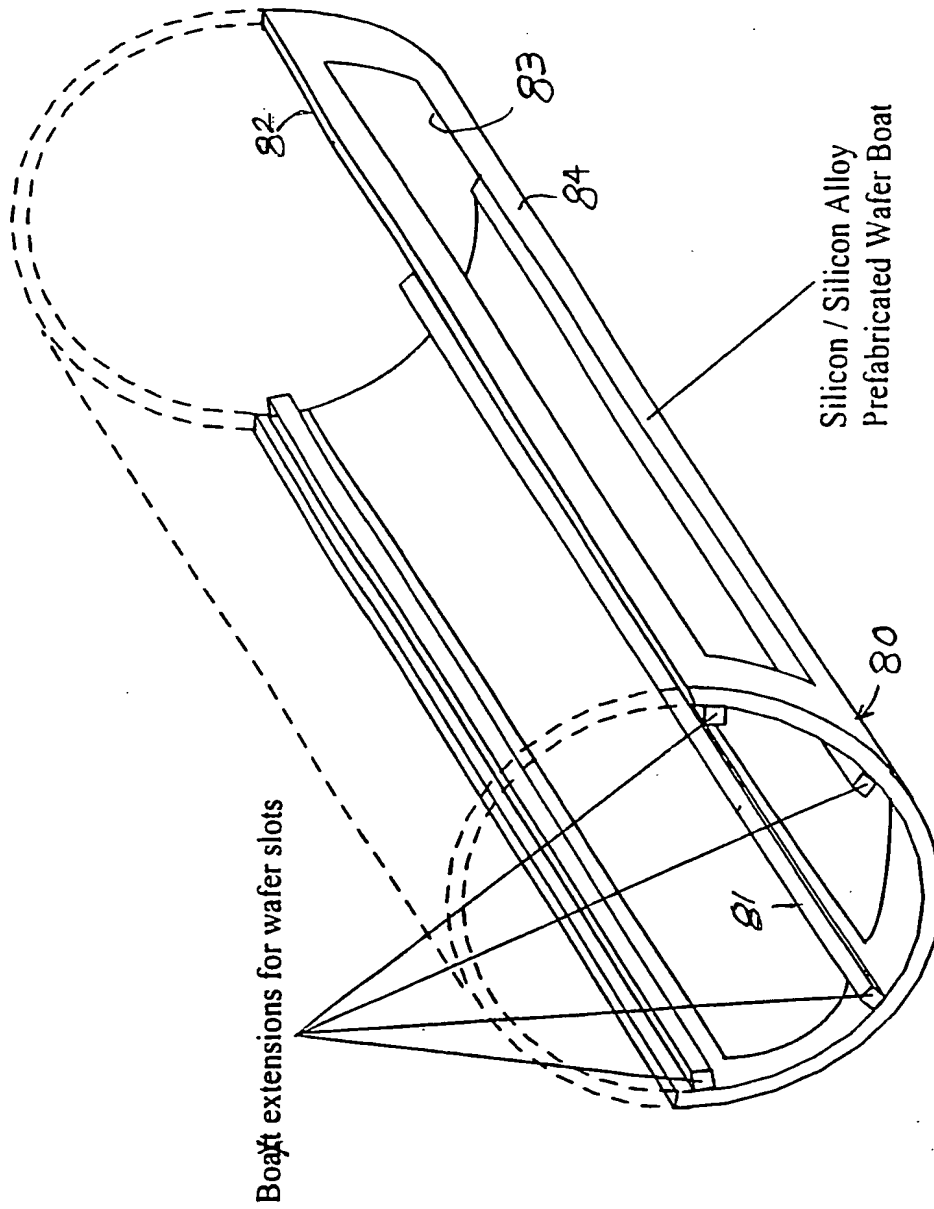


FIG. 9

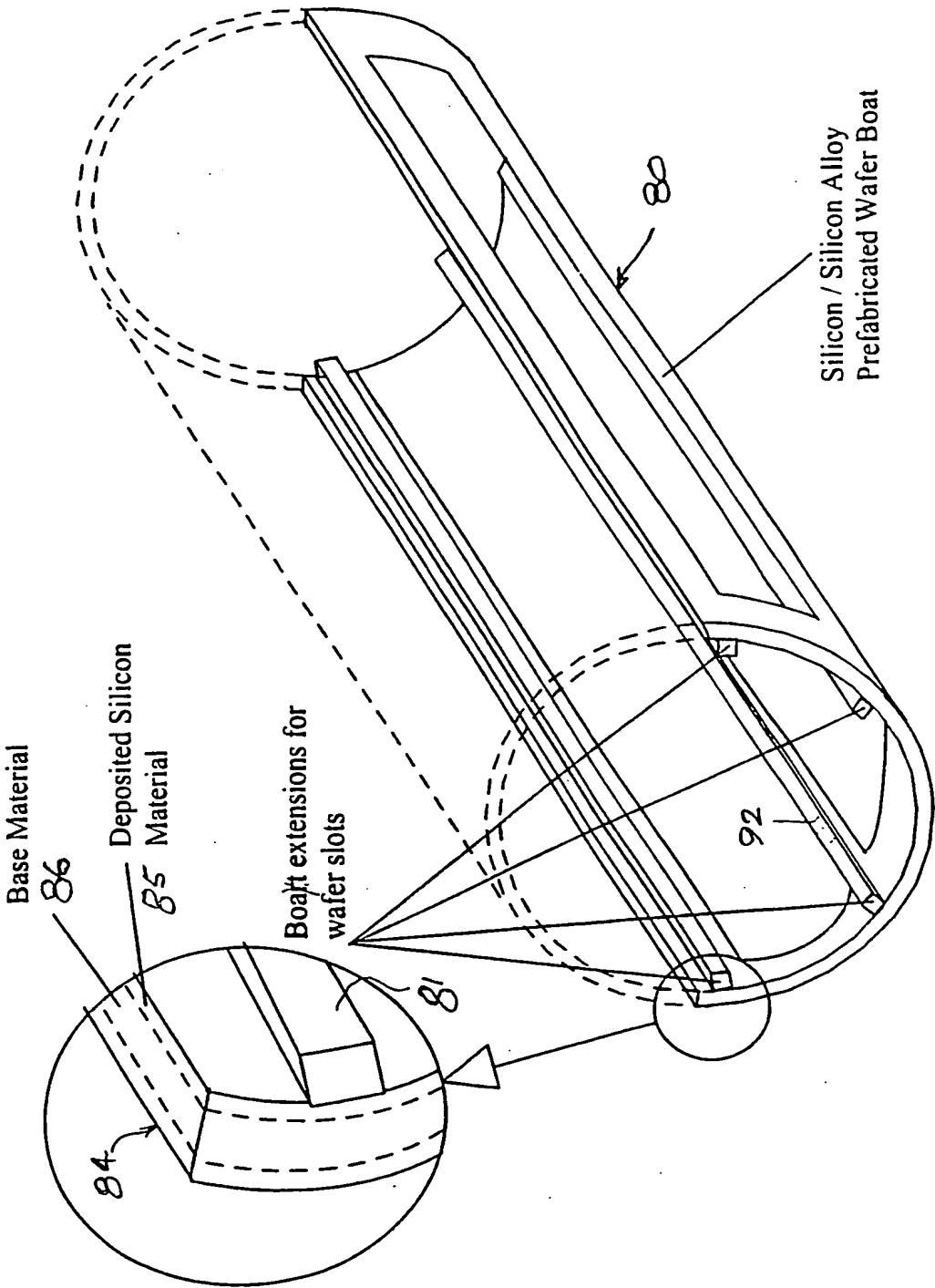


FIG. 10

11/20

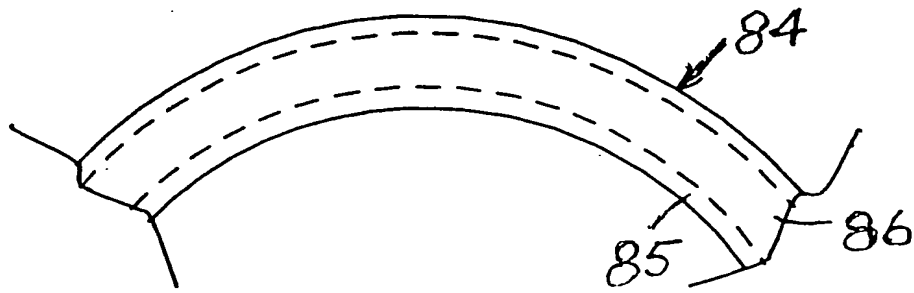


FIG. 11

12/20

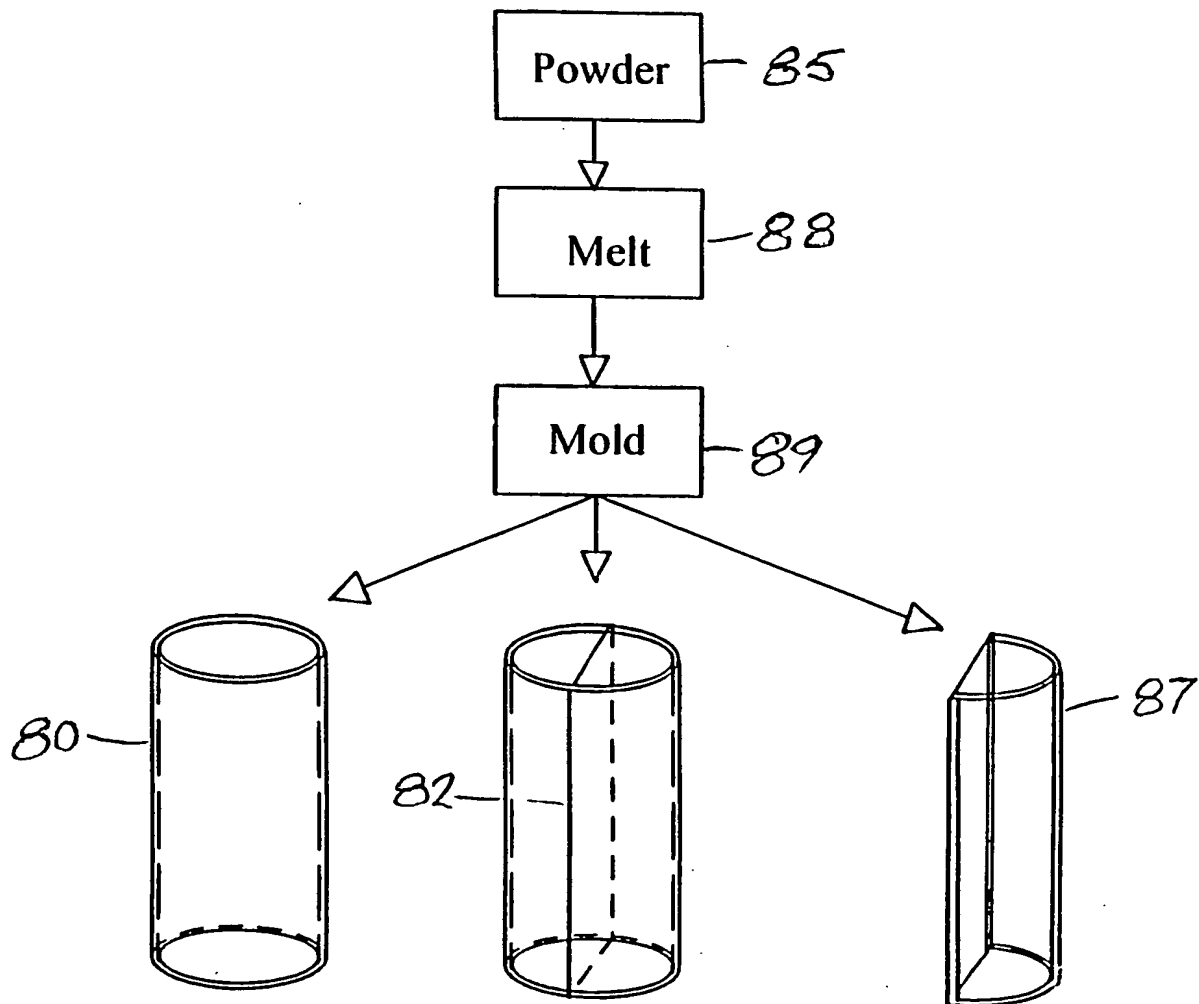


FIG. 12

13/20

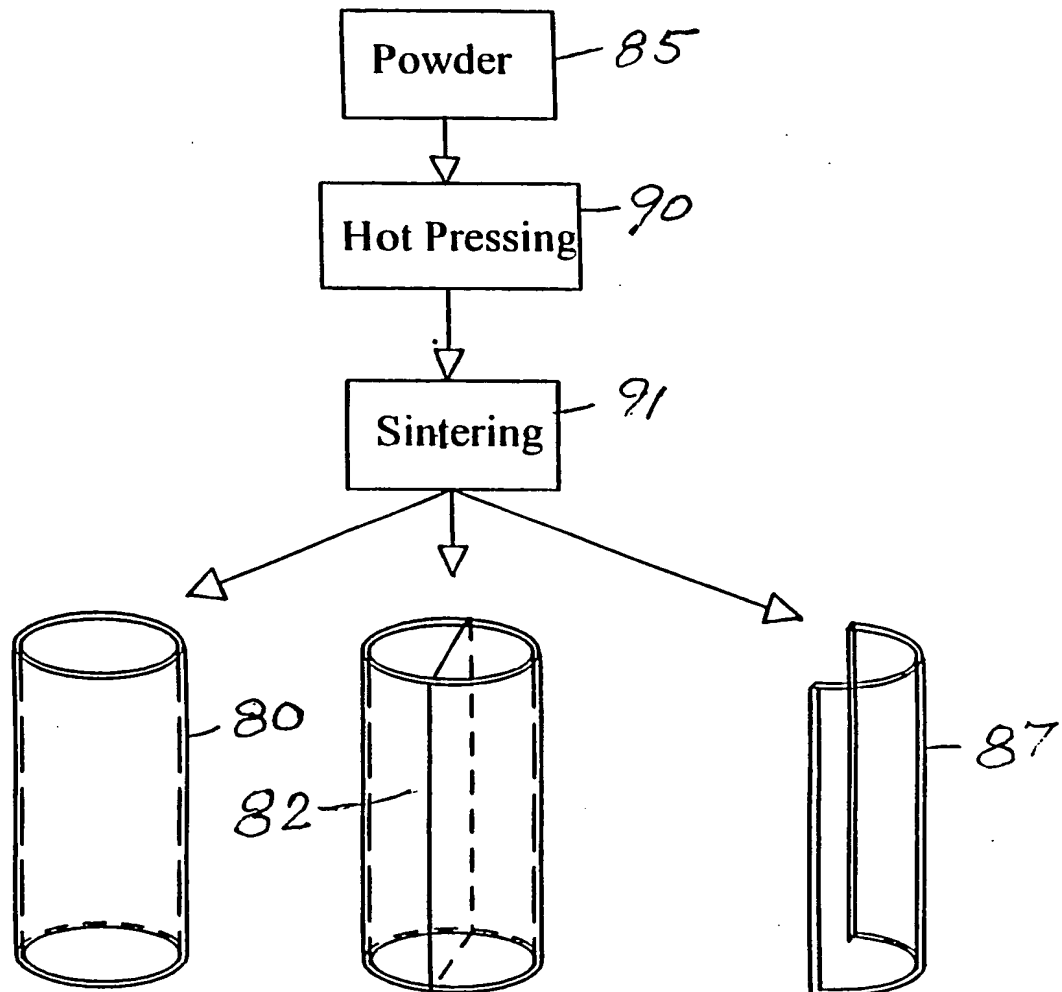


FIG. 13

14/20

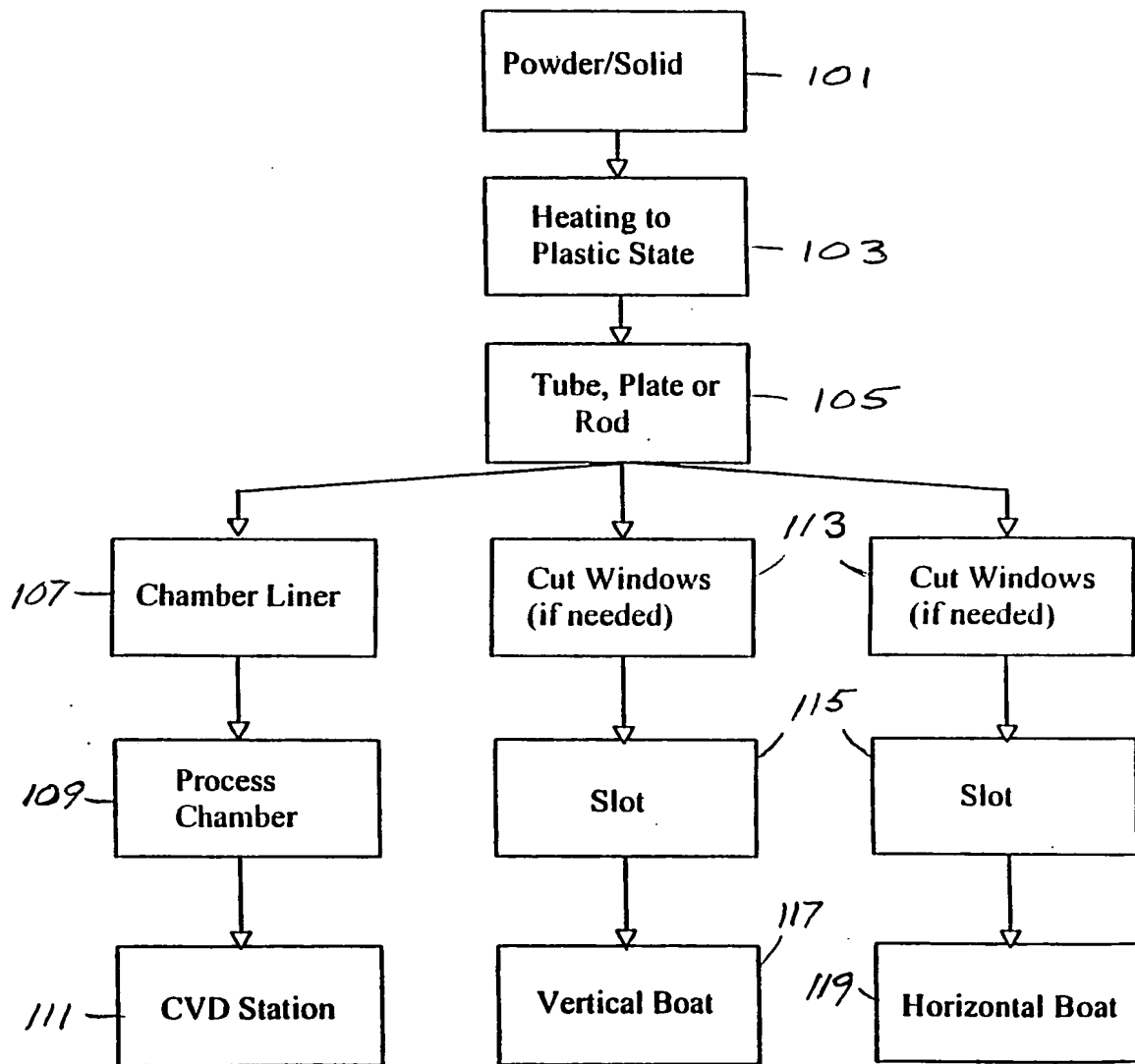
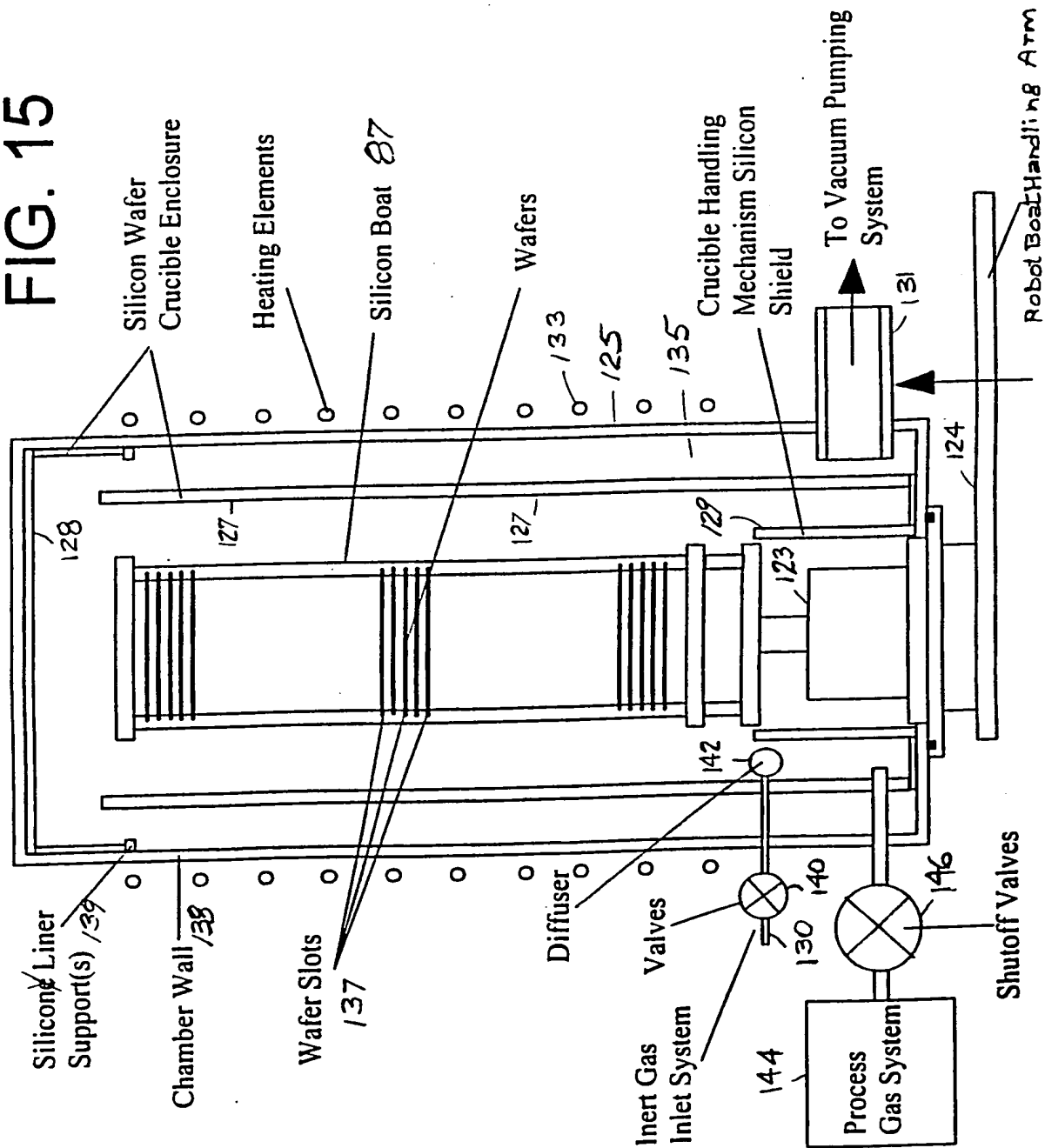
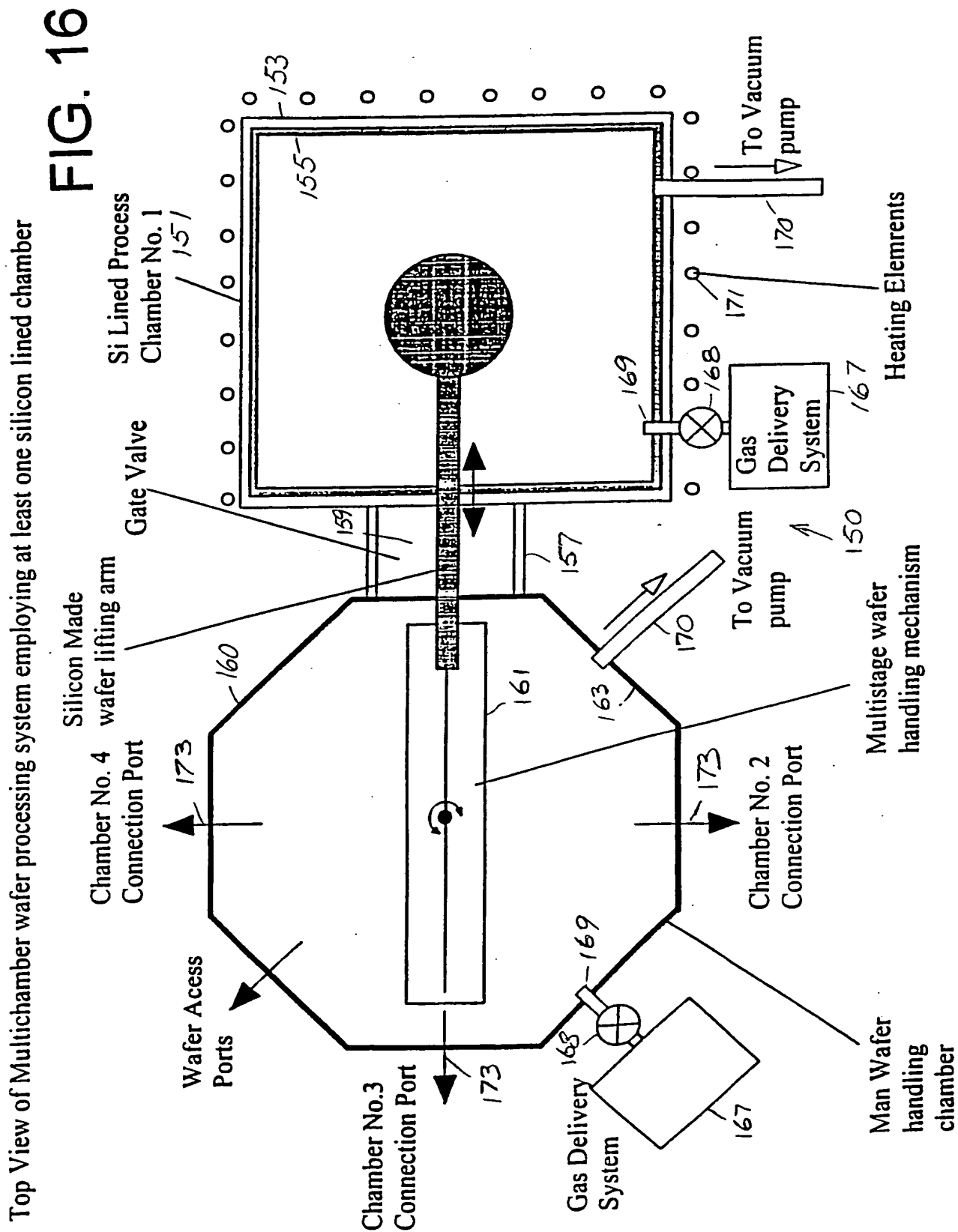


FIG. 14

FIG. 15





Epitaxial/CVD chamber fabrication process

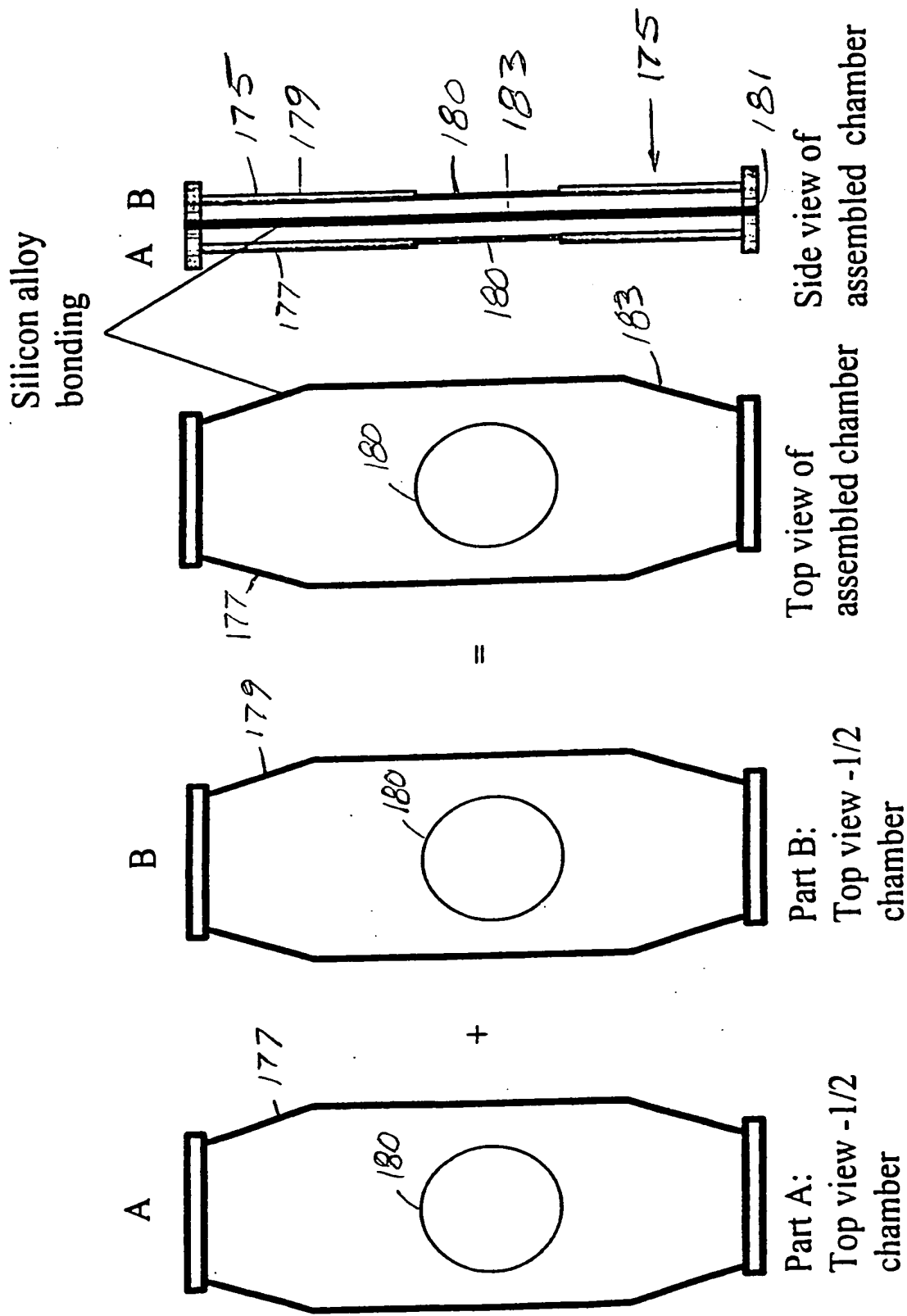


FIG. 17

Top View of Multichamber epitaxial wafer processing system employing at least one silicon made chamber

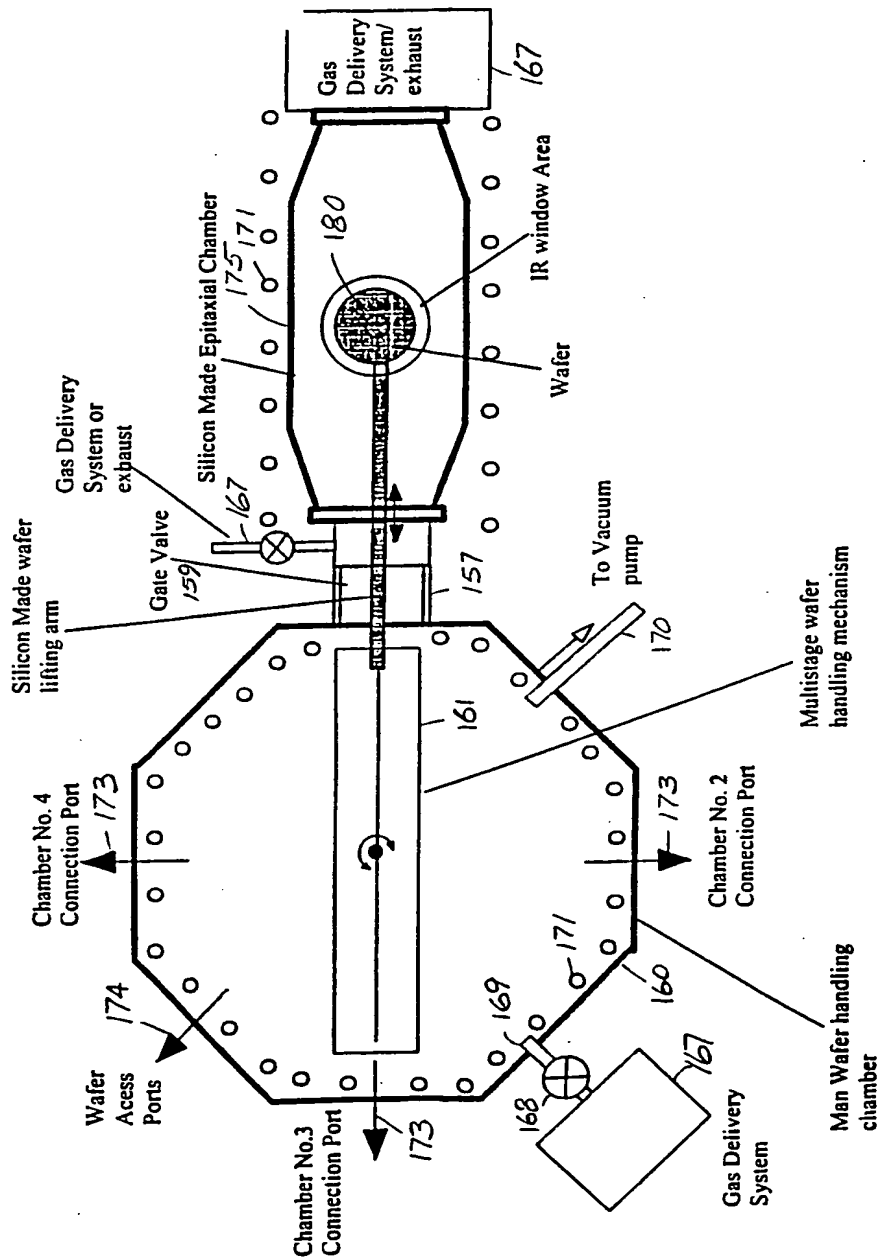


FIG. 18

Side View of Multichamber epitaxial wafer processing system employing at least one silicon made chamber

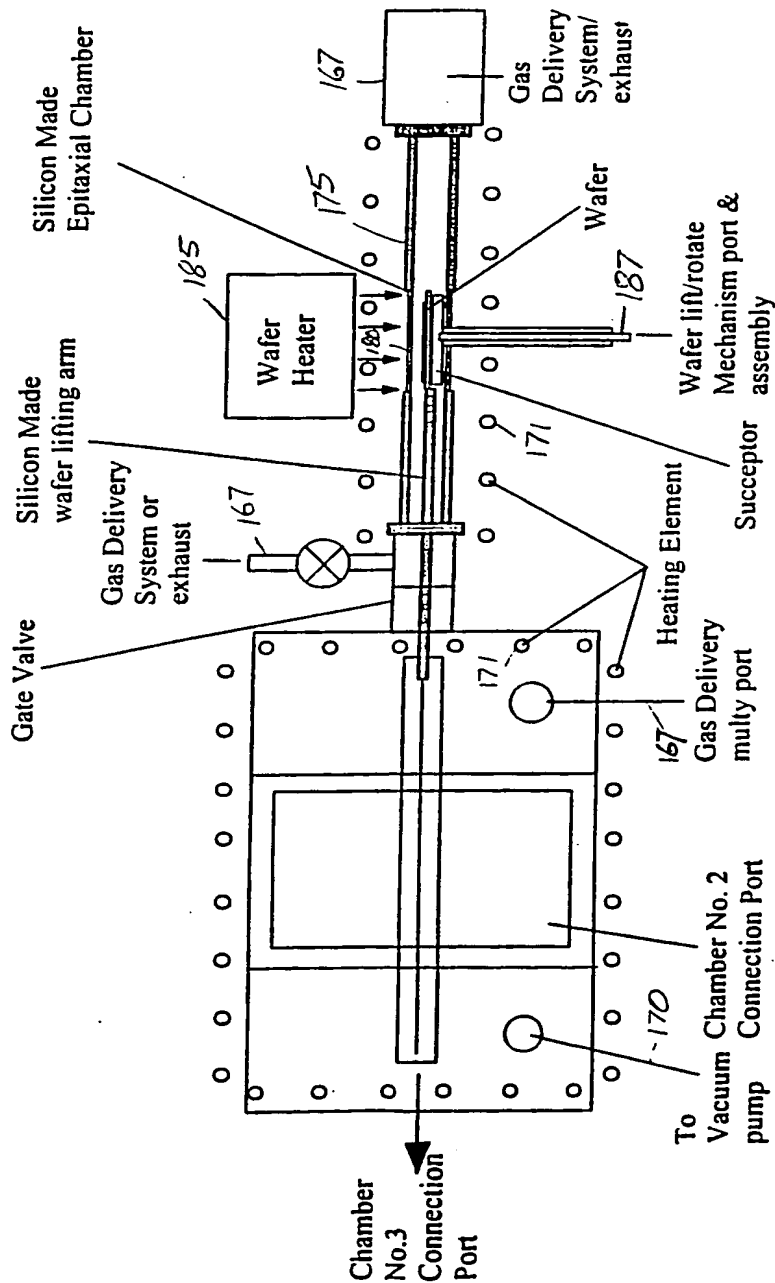
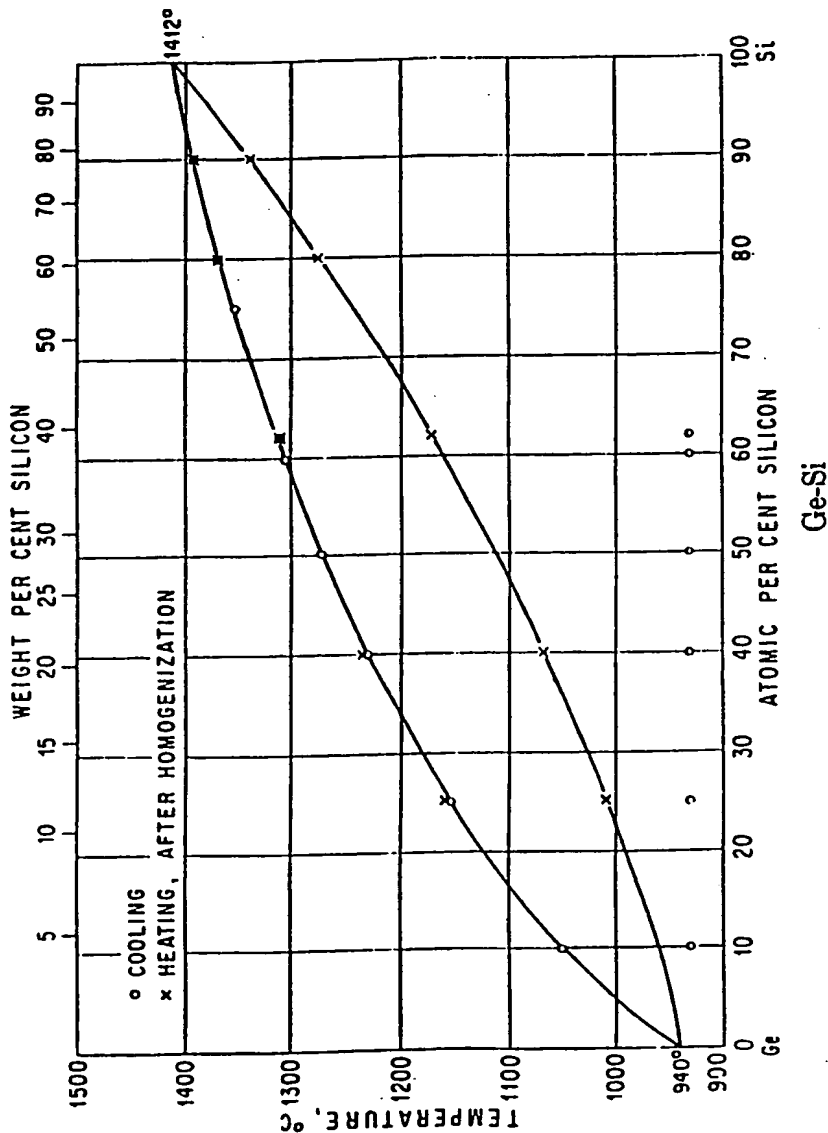


FIG. 19

The diagram was established by thermal and X-ray analysis
Because of the absence of diffusion during solidification, the solidus temperature



on normal cooling from the molten state was found at a temperature about 10°C
below the melting point of Ge, in alloys up to about 60 at. % Si. Heating curves

FIG. 20